| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|---------|---------------------------------|---|---------------------|---------|------------------|
| L1 | 32 | 257/e21.575 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:10 |
| L8 | 1 | "20040089924".PN. | US-PGPUB | ADJ | ON | 2007/05/10 21:15 |
| L9 | 2 | ("6930394").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR . | OFF | 2007/05/10 21:15 |
| L10 | 4 | "6930394" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:15 |
| L11 | 8699 | misfet | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:17 |
| L12 | 2588412 | wir\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:17 |
| L13 | 2631 | L11 and L12 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:17 |
| L14 | 799199 | insulat\$3 with (film or layer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:17 |

Page 1

| L15 | 142255 | L14 with (via or hole or trench) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:17 |
|-----|--------|--|---|-----|-----|------------------|
| L16 | 122 | L15 and L13 and titanium nitride and aluminum and pattern\$3 and semiconductor and damascene | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:18 |
| S1 | 1312 | (438/618).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/02 19:19 |
| S2 | 798 | (438/623).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:27 |
| S3 | 1532 | (438/778).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:26 |
| S4 | 1007 | (438/758).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/02 19:20 |
| S5 | 894 | (438/787).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:27 |
| S6 | 6046 | silane and cvd and wir\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2006/08/02 19:27 |

| S7 | 210 | silicon-rich with silicon adj oxide | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2006/08/02 19:28 |
|-----|------|-------------------------------------|---|-----|----|------------------|
| S8 | . 12 | S6 and S7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2006/08/02 19:28 |
| S9 | 3 | S6 and S7 and sion | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2006/08/02 19:30 |
| S10 | 1 | UCHIKOSHI-KEN.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S11 | 8 | SUWANAI-NAOKATSU .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S12 | 1 | TACHIGAMI-ATSUSHI .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S13 | 41 | HOTTA-KATSUHIKO .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S14 | 37 | SAHARA-MASASHI .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |

| S15 | 1180 | SATO-KAZUHIKO .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
|-----|------|------------------------|---|-----|------|------------------|
| S16 | 4 | 257/e21.575 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2006/08/02 19:46 |
| S17 | 3 | UCHIKOSHI-KEN.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S18 | 3 | TACHIGAMI-ATSUSHI .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S19 | 53 | HOTTA-KATSUHIKO .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S20 | 42 | SAHARA-MASASHI .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |
| S21 | 1217 | SATO-KAZUHIKO .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON . | 2007/05/08 19:26 |
| 522 | 10 | SUWANAI-NAOKATSU .in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:26 |

| | I | | r | | | |
|-----|---------|---------------------------------|---|-------|-----|------------------|
| S23 | 1728 | (438/778).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:26 |
| S24 | 964 | (438/787).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:27 |
| S25 | 847 | (438/623).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:37 |
| S26 | 1478 | (438/618).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/08 19:37 |
| S27 | 8697 | misfet | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:38 |
| S28 | 2587014 | wir\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ . | ON | 2007/05/08 19:38 |
| S29 | 2630 | S27 and S28 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:38 |
| S30 | 798764 | insulat\$3 with (film or layer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:39 |

| 634 | 2222 | C20 4 C20 | 116 566115 | AD3 | 011 | 2007/05/00 10 20 |
|-------|--------|--|---|-------|-----|------------------|
| S31 | 2239 | S30 and S29 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:39 |
| 532 | 142131 | S30 with (via or hole or trench) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:40 |
| S33 | 1469 | S32 and S29 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:41 |
| S34 | 515 | S32 and S29 and titanium nitride | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ . | ON | 2007/05/08 19:41 |
| S35 | 0 | S32 and S29 and titanium nitride and alumninum | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:41 |
| S36 | 401 | S32 and S29 and titanium nitride and aluminum | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:42 |
| S37 - | 398 | S32 and S29 and titanium nitride and aluminum and pattern\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:42 |
| 538 | 398 | S32 and S29 and titanium nitride and aluminum and pattern\$3 and semiconductor | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/10 21:17 |

Page 6

| S39 | 92 | S32 and S29 and titanium nitride and aluminum and pattern\$3 and semiconductor and silane | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:44 |
|-----|----|---|---|-----|----|------------------|
| S40 | 91 | S32 and S29 and titanium nitride and aluminum and pattern\$3 and semiconductor and silane and cvd | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:44 |
| S41 | 81 | S32 and S29 and titanium nitride and aluminum and pattern\$3 and semiconductor and floating | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:45 |
| S42 | 0 | S32 and S29 and titanium nitride and aluminum and pattern\$3 and semiconductor and floatingwith state | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:45 |
| S43 | 33 | S32 and S29 and titanium nitride and aluminum and pattern\$3 and semiconductor and floating with state | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2007/05/08 19:45 |